

Slic™ Foil was developed for etching, milling and laser cutting SMT stencils. The microstructure and low residual stress ensure maximum performance and printability for every application.

NO. 1 WORLDWIDE

Our unique approach to metallurgy, from alloy selection to foil manufacturing and frame mounting, enables us to provide stencil materials that help control the printing process and reduce SMT defects:

- The industry's tightest thickness and flatness tolerances guarantee predictable area ratios and transfer efficiencies across the entire print area
- Stress-relieved foils resist heat distortion from laser cutting, offering superior flatness to optimize gasketing and registration
- Proprietary rolling and annealing processes deliver consistent materials for dependable and repeatable performance

PRODUCT SELECTOR GUIDE

	Slic	UltraSlic FG
Miniaturised or high-density assembly		•
Area ratios <0.60		•
General SMT, lead pitches ≥ 0.5mm, leadless pitches ≥ 1.0mm	•	•
Stepped stencil for μBGA, CSP, QFN, BTC		•
Uniform foil thickness ≥150μm	•	•
Powder Size Type: 5, 6		•
Powder Size Type: 3, 4	•	•

SPECIFICATIONS

- **Gauges:** 0.02 to 0.500 (0.8 mil to 2σ mil)
- **Sizes:** Widths up to 690mm
- **Availability:** Worldwide

QUALITY COMMITMENT

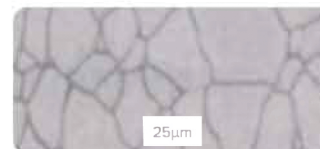
- Every BlueRing team member is committed to providing the highest quality products and services
- BlueRing is ISO-9001 Certified
- Specialized manufacturing processes are continuously monitored and statistically controlled
- All product are inspect and verified prior to shipment

REPEATABILITY

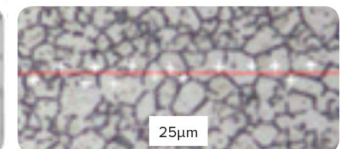
Slic™ is the world's first SS alloy developed specifically for laser-cut SMT stencils. Harder and more durable than standard SS, Slic™ provides longer life, especially in demanding production processes

Repeatability is the key to optimizing print performance:

- Thickness tolerance of +/- 2% is the tightest in the industry, with > 6σ repeatability
- Controlled surface roughness of < 0.15μm maintains paste rolling characteristics from stencil to stencil
- Uniform grain structure and low residual stress ensure consistent response to tensioning, chemical etching, laser cutting and printing processes



Standard SS Microstructure
Grain Size: 15-30μm



Slic™ Microstructure Grain
Grain Size: 7-11μm

IDEAL FOR STANDARD STENCIL STEPS

- **Top side:** connectors, shields, larger SMT components
- **Bottom side:** cavity relief for labels and topographical features